

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	("20040061230" "6908829").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:05
L2	19	("20040061230" "5413962" "5695810" "5708303" "5900668" "5953626" "6667552" "6696758" "6908829").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:05
L3	1359	257/762.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:06
L4	1438	257/750.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:15
L5	4247	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:19
L6	95	interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:40
L7	95	L6 and metal	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:40
L8	95	L7 and layers	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:40
L9	51	L8 and (electroless adj deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:40
L10	51	L9 and ((cobalt or nickel) near\$3 via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:40

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L11	51	L10 and (electroless adj deposition)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:40
L12	0	(apparatus and ((first adj layer) with interconnect) and ((second adj layer) with interconnect) and ((second adj layer) with sublayer) and (sublayer with ILD) and (sublayer with air) and ((third adj layer) with (air adj gap)) and (shunt with (first adj material)) and (shunt with interconnects) and (material with electromigration)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:53
S1	963	257/762.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:06
S2	1175	257/750.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:15
S3	2970	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:19
S4	2	("5695810").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 18:52
S5	1	("0168747").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 18:52
S6	1	("20030168747").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 19:01
S7	53	(air adj gap) and interconnect and ILD	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/12 13:20

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S8	2	S7 and (via with (cobalt or nickel))	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 19:02
S9	0	("6667552").URPN.	USPAT	OR	ON	2004/11/28 19:11
S10	22	("4898841" "4954214" "5117276" "5413962" "5483104" "5708303" "5882963" "5900668" "5936295" "5950102" "5953626" "6037248"). PN. OR ("6245658").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/28 19:12
S11	13	S10 and (air adj gap)	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/28 19:12
S12	0	(air adj gap) and interconnect and ILD and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:19
S13	0	(air adj gap) and interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:19
S14	60	interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/12 13:31
S15	60	S14 and metal	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/12 13:22
S16	60	S15 and layers	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/12 13:22
S17	32	S16 and (electroless adj deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/12 13:23
S18	32	S17 and ((cobalt or nickel) near\$3 via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/12 13:31
S19	32	S18 and (electroless adj deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
S20	87	interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55

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S21	87	S20 and metal	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
S22	87	S21 and layers	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
S23	47	S22 and (electroless adj deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
S24	47	S23 and ((cobalt or nickel) near\$3 via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 16:55
S25	47	S24 and (electroless adj deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:19
S26	1301	257/762.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:07
S27	1403	257/750.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:12
S28	4056	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:15
S29	0	(air adj gap) and interconnect and ILD and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:19
S30	0	(air adj gap) and interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:20
S31	31	(air adj gap) and interconnect and ((cobalt or nickel) with via) and (electroless with deposition)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:20

EAST Search History

S32	0	(apparatus and ((first adj layer) with interconnect) and ((second adj layer) with interconnect) and ((second adj layer) with sublayer) and (sublayer with ILD) and (sublayer with air) and ((third adj layer) with (air adj gap)) and (shunt with (first adj material)) and (shunt with interconnects) and (material with electromigration)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 19:53
S33	0	(apparatus and ((first adj layer) with interconnect) and ((second adj layer) with interconnect) and ((second adj layer) with sublayer) and (sublayer with ILD) and (sublayer with air) and ((third adj layer) with (air adj gap)) and (shunt with (first adj material)) and (shunt with interconnects) and (material with electromigration))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/15 17:24